

> Mechanical Specification:

(1) Dimension

- Chip size: $550 \pm 25 \text{ } \mu\text{m} \times 1110 \pm 25 \text{ } \mu\text{m}$
- Thickness: $150 \pm 10 \text{ } \mu\text{m}$
- P bonding pad: $76 \pm 10 \text{ } \mu\text{m}$
- N bonding pad: $76 \pm 10 \text{ } \mu\text{m}$

(2) Metallization

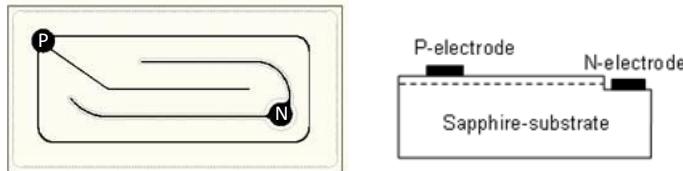
- Topside P electrode: Au alloy
- Topside N electrode: Au alloy

Features:

- High radiant flux
- Long operation life
- Lambertian radiation

Applications:

- Backlight



> Electro-optical Characteristics at 25°C: ⁽¹⁾

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	Vf1	If = 10μA	1.6	-	-	V
	Vf2	If = 350mA	-	3.3	3.4	V
Reverse Current	Ir	Vr = 5V	-	-	2.0	μA
Dominant Wavelength ⁽²⁾	λd	If = 350mA	445	-	460	nm
Spectra Half-width	Δλ	If = 350mA	-	25	-	nm
Radiant Flux ⁽³⁾⁽⁴⁾	Po	If = 350mA	650	-	660	mW
			660	-	680	
			680	-	700	
			700	-	725	

Note:

(1) ESD protection during chip handling is recommended.

(2) Basically, the wavelength span is 15nm; however, customers' special requirements are also welcome.

(3) Radiant flux is determined by using an Ag-plated TO-can header without an encapsulant.

(4) Radiant flux measurement allows a tolerance of ±15%.

> Absolute Maximum Ratings:

Parameter	Symbol	Condition	Rating	Unit
Forward DC Current	If	T _a = 25°C	≤ 500	mA
Reverse Voltage	V _r	T _a = 25°C	≤ 5	V
Junction Temperature	T _j	-	≤ 125	°C
Storage Temperature	T _{stg}	Chip	-40 ~ +85	°C
		Chip-on-tape/storage	5 ~ 35	°C
		Chip-on-tape/transportation	-20 ~ +65	°C
Temperature during Packaging	-	-	280(<10sec)	°C

Note: Maximum ratings are package dependent. The above maximum ratings were determined using a Metal Core Printed Circuit Board (MPCB) without an encapsulant.
Stresses in excess of the absolute maximum ratings such as forward current and junction temperature may cause damage to the LED.

> Characteristic Curves:

Fig.1 – Relative luminous Intensity vs. Forward Current

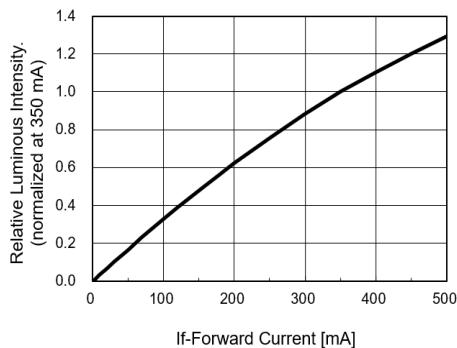


Fig.2 – Forward Current vs. Forward Voltage

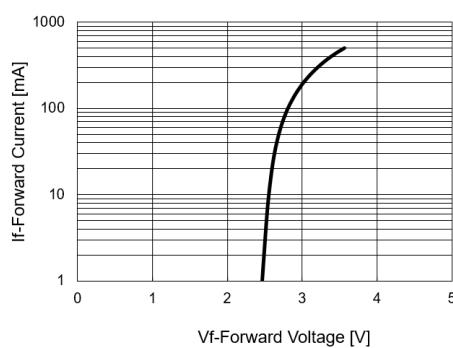


Fig.3 – Relative Intensity (@350mA) vs. Ambient Temperature

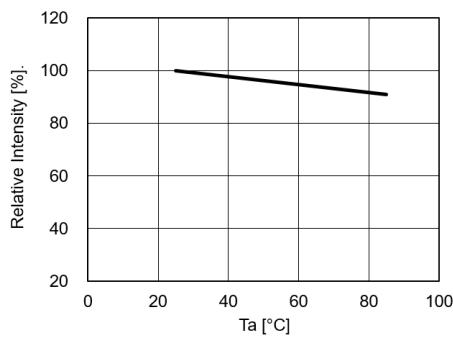


Fig.4 – Forward Voltage (@350mA) vs. Ambient Temperature

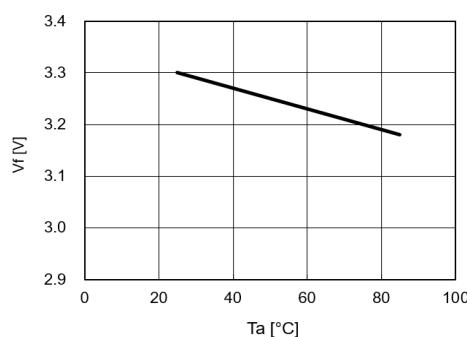


Fig.5 – Dominant Wavelength (@350mA) vs. Ambient Temperature

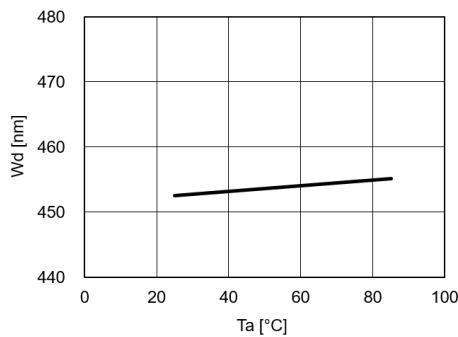


Fig.6 – Maximum Driving Forward DC Current vs. Ambient Temperature (De-rating based on T_j max. = 125°C)

